



Its low dissipation factor extends the usefulness of RT/duroid 5870 and 5880 laminates to Ku-band and above.

RT/duroid 5870 and 5880 laminates are easily cut, sheared and machined to shape. They are resistant to all solvents and reagents, hot or cold, normally used in etching printed

may also be specified.

When ordering RT/duroid 5870 and 5880 laminates, it is important to specify dielectric thickness, tolerance, rolled, electrodeposited or reverse treated copper foil, and weight of copper foil required.

Data Sheet



Features:

Some Typical Applications:

S		S		S	C	C	-S	C	C
0.005" (0.127mm)	0.031" (0.787mm)	18" X 12" (457 X 305mm)	18" X 24" (457 X 610mm)	1/2 oz. (18µm) and 1 oz. (35µm)	1/4 oz. (9 µm) electrodeposited copper foil	1/2 oz. (18µm), 1 oz. (35µm) and 2 oz. (70µm) reverse treat	1/2 oz. (18µm), 1 oz. (35µm) and 2 oz. (70µm) reverse treat	1/2 oz. (18µm), 1 oz. (35µm) and 2 oz. (70µm) reverse treat	1/2 oz. (18µm), 1 oz. (35µm) and 2 oz. (70µm) reverse treat
0.010" (0.254mm)	0.062" (1.575mm)	Non-standard sizes may be available up to 18" X 48" (457 X 1219 mm)	Thick metal claddings may be available based on dielectric and plate thickness. Contact customer service for more information on available non-standard and custom thicknesses, claddings and panel sizes	electrodeposited and rolled copper foil	2 oz. (70µm) electrodeposited and rolled copper foil				
0.015" (0.381mm)									
0.020" (0.508mm)									
Non-standard thicknesses are available									